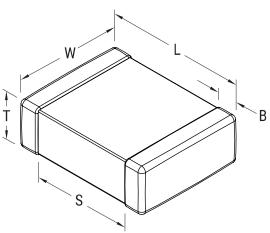


SMD Comm X8G HT150C Flex, Ceramic, 1,500 pF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm





Click here for the 3D model.		
Dimensions		
Chip Size	0603	
L	1.6mm +/-0.17mm	
W	0.8mm +/-0.15mm	

W	0.8mm +/-0.15mm	
Т	0.85mm +/-0.07mm	
S	0.4mm MIN	
В	0.45mm +/-0.15mm	
Packaging Specifications		

Packaging Specifications		
Packaging	T&R, 330mm, Paper Tape	
Packaging Quantity	10000	

General Information			
Series	SMD Comm X8G HT150C Flex		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Flexible Termination		
Marking	No		
AEC-Q200	No		
Typical Component Weight	4.6 mg		
Shelf Life	78 Weeks		
MSL	1		

Specifications	
Capacitance	1,500 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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